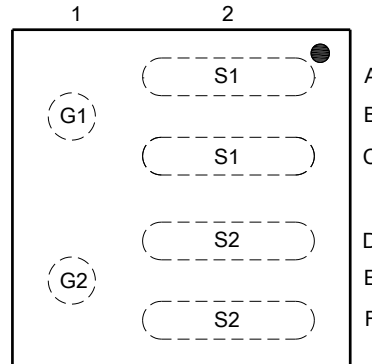
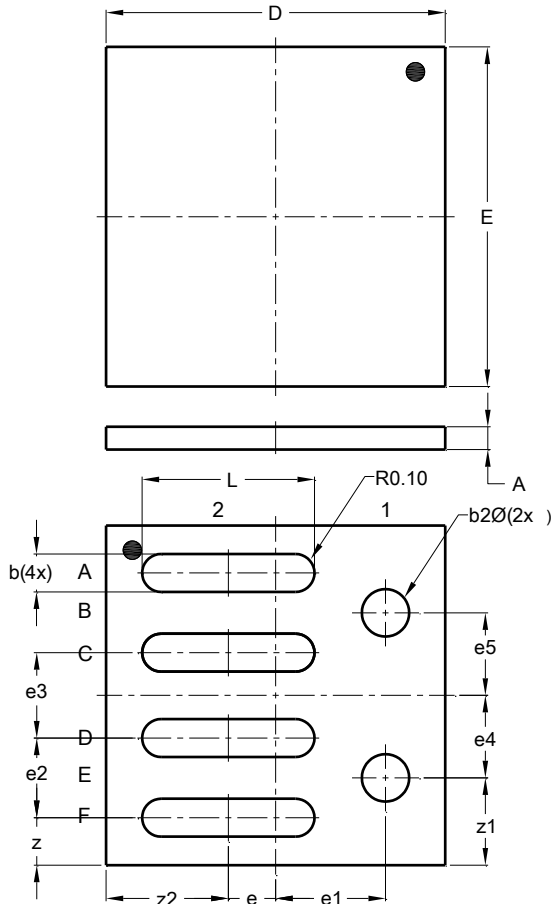


Package Outline Dimensions

X4-DSN1818-6

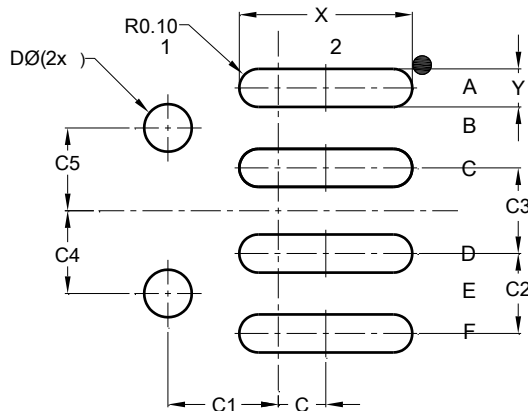


Pin Assignment	
A2	S1
B1	G1
C2	S1
D2	S2
E1	G2
F2	S2

X4-DSN1818-6			
Dim	Min	Max	Typ
A	0.05	0.15	0.10
b	0.17	0.23	0.20
b2	0.22	0.28	0.25
D	1.76	1.82	1.79
E	1.76	1.82	1.79
e	--	--	0.25
e1	--	--	0.58
e2	--	--	0.42
e3	--	--	0.45
e4	--	--	0.435
e5	--	--	0.435
L	0.88	0.94	0.91
z	--	--	0.25
z1	--	--	0.46
z2	--	--	0.645
All Dimensions in mm			

Suggested Pad Layout

X4-DSN1818-6



Dimensions	Value (in mm)
C	0.250
C1	0.580
C2	0.420
C3	0.450
C4	0.435
C5	0.435
D	0.250
X	0.910
Y	0.200

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.